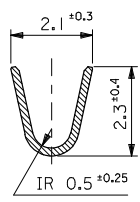
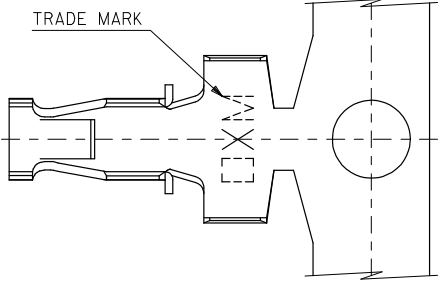
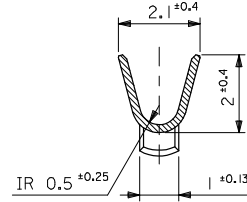


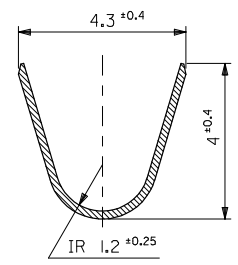
10 9 8 7 6 5 4 3 2 1



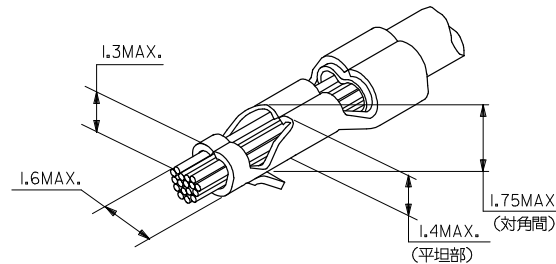
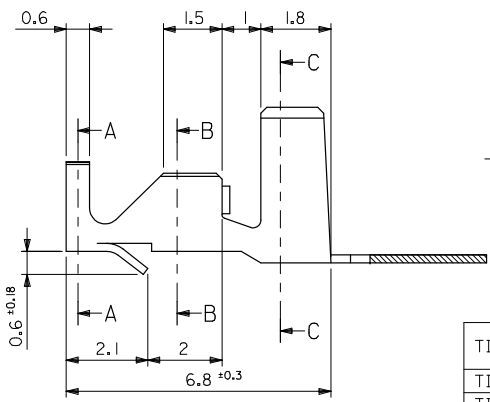
SECT. A-A



SECT. B-B



SECT. C-C



压着外觀図  
OUTSIDE VIEW OF CRIMP

NOTES

1. 推奨プリント基板穴径:  $\phi 1.8^{+0.1}$   
RECOMMENDED P.C.B. HOLES:  $\phi 1.8^{+0.1}$
2. 推奨プリント基板厚:  $t1.57^{+0.2}$   
RECOMMENDED P.C.B. THICKNESS:  $1.57^{+0.2}$
3. 材料の厚み: 0.203  
MATERIAL THICKNESS: 0.203

TIN-LEAD(90-10) 3.8 $\mu$ m MIN. OVER NICKEL 1.3 $\mu$ m MIN.	PHOSPHOR BRONZE	CHAIN	39-00-0277	5298PBPT
	BRASS	CHAIN	39-00-0276	5298PT
TIN 0.9 $\mu$ m MIN. REFLOW TREATMENT (PRE-PLATED)	PHOSPHOR BRONZE	CHAIN	39-00-0230	5298PBT
TIN 0.9 $\mu$ m MIN. OVER COPPER 0.5 $\mu$ m MIN. (PRE-PLATED)	BRASS	CHAIN	08-70-0106	5298T
PLATING	MATERIAL	FORM	EDP NO.	ENG. NO.

材料 MATERIAL SEE TABLE & NOTE
仕上げ FINISH
適用電線範囲 WIRE RANGE AWG #18-22
被覆外径 INS. RANGE $\phi 1.7-3.05$

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)
EC NO: J2008-3347	2008/03/21	10 UNDER $\pm 0.2$
DRW: NABEI	2008/03/24	10 OVER 30 UNDER $\pm 0.25$
CHKD: THAYAMA	2008/03/24	30 OVER $\pm 0.3$
APPR: NIKITA		ANGULAR $\pm 3^\circ$
REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY H. HIRAMOTO	DATE '91/09/05	TITLE LOW PROFILE PC BOARD CRIMP PIN	
CHECKED BY H. HIRAMOTO	DATE '93/07/06	MOLEX INCORPORATED	
APPROVED BY M. FUKUSHIMA	DATE '93/07/06	DOCUMENT NO. SD-5298-001	SHEET NO. 1 OF 1
MATERIAL NO.	SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	